2SK3211(L),2SK3211(S)

Silicon N Channel MOS FET High Speed Power Switching

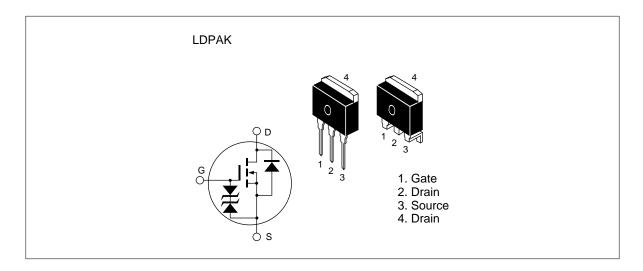
HITACHI

ADE-208-761(Z) Target Specification, 1st. Edition Dec. 1, 1998

Features

- Low on-resistance $R_{DS} = 60 m\Omega \text{ typ.}$
- High speed switching
- 4V gate drive device can be driven from 5V source

Outline



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Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	200	V	
Gate to source voltage	$V_{\rm GSS}$	±20	V	
Drain current	I _D	25	A	
Drain peak current	Note1	100	A	
Body-drain diode reverse drain current	I _{DR}	25	A	
Avalanche current	Note3	25	A	
Avalanche energy	E _{AR} Note3	41	mJ	
Channel dissipation	Pch Note2	100	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %

- 2. Value at $Tc = 25^{\circ}C$
- 3. Value at Tch = 25°C, Rg \geq 50 Ω

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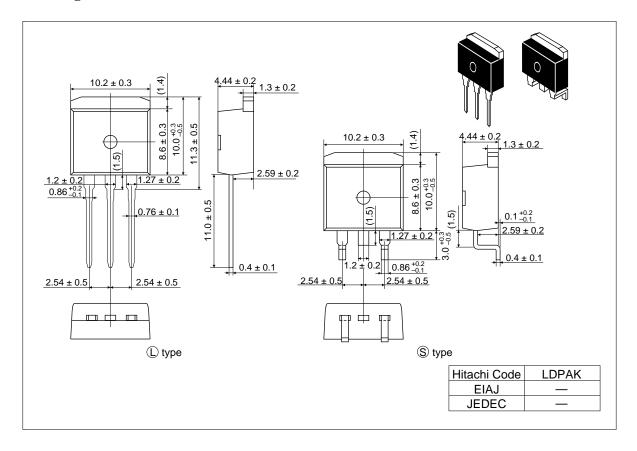
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	200	_	_	V	$I_{D} = 10 \text{mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μА	$V_{GS} = \pm 16V, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	V _{DS} = 200 V, V _{GS} = 0
Gate to source cutoff voltage	$V_{\rm GS(off)}$	1.0	_	2.5	V	$I_D = 1 \text{mA}, V_{DS} = 10 \text{V}$
Static drain to source on state	R _{DS(on)}	_	0.06	0.075	Ω	$I_D = 15A, V_{GS} = 10V^{Note4}$
resistance	R _{DS(on)}	_	0.065	0.085	Ω	I_D =15A, V_{GS} = 4V Note4
Forward transfer admittance	y _{fs}	18	30	_	S	$I_{D} = 15A, V_{DS} = 10V^{Note4}$
Input capacitance	Ciss	_	2420	_	pF	V _{DS} = 10V
Output capacitance	Coss	_	790	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	340	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	60	_	ns	I _D =15A, V _{GS} = 10V
Rise time	t _r	_	230	_	ns	$R_L = 3\Omega$
Turn-off delay time	t _{d(off)}	_	610	_	ns	_
Fall time	t _f	_	230	_	ns	_
Body-drain diode forward voltage	V_{DF}	_	0.95	_	V	$I_F = 25A, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	230	_	ns	$I_F = 25A, V_{GS} = 0$ diF/ dt =50A/ μ s

Note: 4. Pulse test

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Package Dimensions (Unit: mm)



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